1. Record Nr. UNISA990002055830203316

Autore	ARIENTI, Alberto
Titolo	Lezioni di economia delle aziende di credito / Alberto Arienti
Pubbl/distr/stampa	Milano : Giuffrè, 1973
Descrizione fisica	IV, 376 p. ; 25 cm
Collana	Università degli studi di Pavia, Istituto di economia aziendale
Disciplina	332
Soggetti	Banche - Economia
Collocazione	332 ARI 3 (IRA 31 110)
Lingua di pubblicazione	Italiano
Formato	Materiale a stampa
Livello bibliografico	Monografia

2. Record Nr. UNINA9910137852403321

Autore	Liu Sheng
Titolo	Modeling and Simulation for Microelectronic Packaging Assembly [[electronic resource]] : Manufacturing, Reliability and Testing
Pubbl/distr/stampa	Chicester, : Wiley, 2011
ISBN	1-299-31442-2 0-470-82782-3 0-470-82781-5
Descrizione fisica	1 online resource (588 p.)
Classificazione	TEC008010
Altri autori (Persone)	LiuYong
Disciplina	621.381046
Soggetti	Microelectronic packaging - Simulation methods Microelectronic packaging -- Simulation methods TECHNOLOGY & ENGINEERING / Electronics / Circuits / General Electrical & Computer Engineering Engineering & Applied Sciences Electrical Engineering
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia

Note generali	Description based upon print version of record.
Nota di contenuto	Modeling and Simulation for Microelectronic Packaging Assembly: Manufacturing, Reliability and Testing; Contents; Foreword by C. P. Wong; Foreword by Zhigang Suo; Preface; Acknowledgments; About the Authors; Part I: Mechanics and Modeling; 1 Constitutive Models and Finite Element Method; 1.1 Constitutive Models for Typical Materials; 1.1.1 Linear Elasticity; 1.1.2 Elastic-Visco-Plasticity; 1.2 Finite Element Method; 1.2.1 Basic Finite Element Equations; 1.2.2 Nonlinear Solution Methods; 1.2.3 Advanced Modeling Techniques in Finite Element Analysis 1.2.4 Finite Element Applications in Semiconductor Packaging Modeling1.3 Chapter Summary; References; 2 Material and Structural Testing for Small Samples; 2.1 Material Testing for Solder Joints; 2.1.1 Specimens; 2.1.2 A Thermo-Mechanical Fatigue Tester; 2.1.3 Tensile Test; 2.1.4 Creep Test; 2.1.5 Fatigue Test; 2.2 Scale Effect of Packaging Materials; 2.2.1 Specimens; 2.2.2 Experimental Results and Discussions; 2.2.3 Thin Film Scale Dependence for Polymer Thin Films; 2.3 Two-Ball Joint Specimen Fatigue Testing; 2.4 Chapter Summary; References 3 Constitutive and User-Supplied Subroutines for Solders Considering Damage Evolution3.1 Constitutive Model for Tin-Lead Solder Joint; 3.1.1 Model Formulation; 3.1.2 Determination of Material Constants; 3.1.3 Model Prediction; 3.2 Visco-Elastic-Plastic Properties and Constitutive Modeling of Underfills; 3.2.1 Constitutive Modeling of Underfills; 3.2.2 Identification of Material Constants; 3.2.3 Model Verification and Prediction; 3.3 A Damage Coupling Framework of Unified Viscoplasticity for the Fatigue of Solder Alloys; 3.3.1 Damage Coupling Thermodynamic Framework 3.3.2 Large Deformation Formulation3.3.3 Identification of the Material Parameters; 3.3.4 Creep Damage; 3.4 User-Supplied Subroutines for Solders Considering Damage Evolution; 3.4.1 Return-Mapping Algorithm and FEA Implementation; 3.4.2 Advanced Features of the Implementation; 3.4.3 Applications of the Methodology; 3.5 Chapter Summary; References; 4 Accelerated Fatigue Life Assessment Approaches for Solders in Packages; 4.1 Life Prediction Methodology; 4.1.1 Strain-Based Approach; 4.1.2 Energy-Based Approach; 4.1.3 Fracture Mechanics-Based Approach; 4.2 Accelerated Testing Methodology 4.2.1 Failure Modes via Accelerated Testing Bounds4.2.2 Isothermal Fatigue via Thermal Fatigue; 4.3 Constitutive Modeling Methodology; 4.3.1 Separated Modeling via Unified Modeling; 4.3.2 Viscoplasticity with Damage Evolution; 4.4 Solder Joint Reliability via FEA; 4.4.1 Life Prediction of Ford Joint Specimen; 4.4.2 Accelerated Testing: Insights from Life Prediction; 4.4.3 Fatigue Life Prediction of a PQFP Package; 4.5 Life Prediction of Flip-Chip Packages; 4.5.1 Fatigue Life Prediction with and without Underfill 4.5.2 Life Prediction of Flip-Chips without Underfill via Unified and Separated Constitutive Modeling
Sommario/riassunto	Although there is increasing need for modeling and simulation in the IC package design phase, most assembly processes and various reliability tests are still based on the time consuming ""test and try out"" method to obtain the best solution. Modeling and simulation can easily ensure virtual Design of Experiments (DoE) to achieve the optimal solution. This has greatly reduced the cost and production time, especially for new product development. Using modeling and simulation will become increasingly necessary for future advances in 3D package development.

	In this book, Liu and Liu allow people

3.

Record Nr.	UNINA9910146209803321
Titolo	Behavioral and brain functions : BBF
Pubbl/distr/stampa	[London], : BioMed Central, 2005-
ISSN	1744-9081
Soggetti	Neurophysiology Neuropsychology Brain - Localization of functions Human behavior Animal behavior Nervous System Physiological Phenomena Nervous System Diseases - psychology Brain - physiology Behavior Behavior, Animal Neurology Behavioral Medicine Periodical Periodicals.
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Periodico
Note generali	Refereed/Peer-reviewed Title from PDF caption (publisher's Web site, viewed June 3, 2005). "Behavioral and brain functions is an open access, peer-reviewed, online journal that encompasses all aspects of neurobiology where the unifying theme is behavior or behavioral dysfunction"--Website, viewed April 27, 2005.